

Ferrite Chip Bead(Lead Free)

FCM0603-Series

ECN HISTORY LIST

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉玲
2.0	14/01/24	變更電鍍錫層厚度 3.0um min. => 3.5um min.	楊祥忠	羅培君	張嘉玲
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲
4.0	16/01/26	增訂可靠度 Thermal shock: (Bead) Step3 : 125±2°C 30±5min	楊祥忠	詹偉特	張嘉玲
5.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲
備 註					

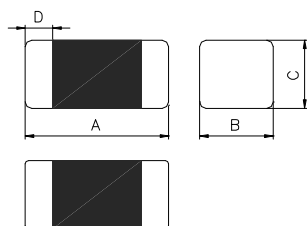
Ferrite Chip Bead(Lead Free) FCM0603-Series

1.Features

1. Monolithic inorganic material construction.
2. Closed magnetic circuit avoids crosstalk.
3. S.M.T. type.
4. Suitable for reflow soldering.
5. Shapes and dimensions follow E.I.A. spec.
6. Available in various sizes.
7. Excellent solder ability and heat resistance.
8. High reliability.
9. 100% Lead(Pb) & Halogen-Free and RoHS compliant.



2.Dimensions



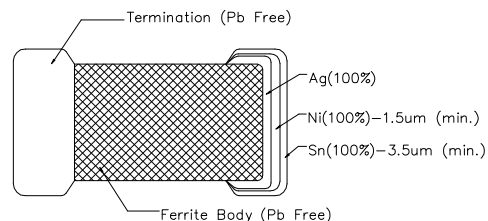
Chip Size	
A	0.60±0.03
B	0.30±0.03
C	0.30±0.03
D	0.15±0.05

Units: mm

3.Part Numbering



- A: Series
 - B: Dimension
 - C: Material
 - D: Impedance
 - E: Packaging
 - F: Rated Current
- L x W
 Lead Free Material
 121=120Ω
 T=Taping and Reel, B=Bulk(Bags)
 02=200mA

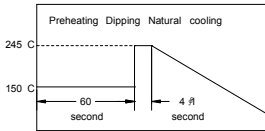
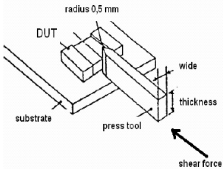


4.Specification

Tai-Tech Part Number	Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
FCM0603WF-220T05	22±25%	60mV/100M	0.065	500
FCM0603WF-330T05	33±25%	60mV/100M	0.07	500
FCM0603WF-800T02	80±25%	60mV/100M	0.40	200
FCM0603WF-121T02	120±25%	60mV/100M	0.45	200
FCM0603WF-241T02	240±25%	60mV/100M	0.65	200
FCM0603WF-601T01	600±25%	60mV/100M	1.20	150
FCM0603KF-102T02	1000±25%	60mV/100M	1.15	220
FCM0603HF-600T02	60±25%	60mV/100M	0.25	200
FCM0603HF-121T02	120±25%	60mV/100M	0.40	200
FCM0603HF-241T02	240±25%	60mV/100M	0.80	200
FCM0603HF-471T01	470±25%	60mV/100M	1.05	100
FCM0603HF-601T01	600±25%	60mV/100M	1.20	100
FCM0603BF-100T02	10±25%	60mV/100M	0.25	200
FCM0603BF-220T02	22±25%	60mV/100M	0.45	200
FCM0603BF-330T01	33±25%	60mV/100M	0.55	150
FCM0603BF-470T01	47±25%	60mV/100M	0.70	150
FCM0603BF-560T01	56±25%	60mV/100M	1.00	100
FCM0603BF-800T01	80±25%	60mV/100M	1.30	100
FCM0603BF-121T01	120±25%	60mV/100M	1.50	100

- Rated current: based on temperature rise test
- In compliance with EIA 595

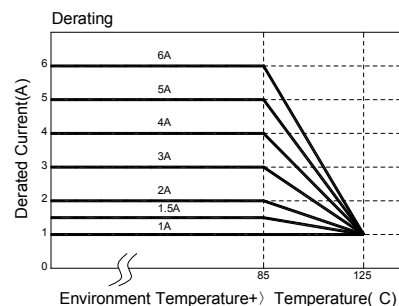
5. Reliability and Test Condition

Item	Performance					Test Condition															
Series No.	FCB	FCM	HCB	GHB	FCA	--															
Operating Temperature	-40~+125°C (Including self-temperature rise)					--															
Transportation Storage Temperature	-40~+125°C (on board)					For long storage conditions, please see the Application Notice															
Impedance (Z)	Refer to standard electrical characteristics list					Agilent4291 Agilent E4991 Agilent4287 Agilent16192															
DC Resistance						Agilent 4338															
Rated Current						DC Power Supply Over Rated Current requirements, there will be some risk															
Temperature Rise Test	Rated Current < 1A ΔT 20°C Max Rated Current ≥ 1A ΔT 40°C Max					1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.															
Resistance to Soldering Heat	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Number of heat cycles: 1 <table border="1"><thead><tr><th>Temperature (°C)</th><th>Time (s)</th><th>Temperature ramp/immersion and emersion rate</th></tr></thead><tbody><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td></tr></tbody></table> Depth: completely cover the termination	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s									
Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate																			
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s																			
Solderability	More than 95% of the terminal electrode should be covered with solder. 					Preheat: 150°C, 60sec. Solder: Sn96.5%-Ag3%-Cu0.5% Solder temperature: 245±5°C Flux for lead free: Rosin. 9.5% Depth: completely cover the termination. Dip time: 4±1sec.															
Terminal strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value 					Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Component mounted on a PCB apply a force >0805inch(2012mm):1kg <=0805inch(2012mm):0.5kg to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.															
Bending	Appearance : No damage. Impedance : within±10% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min															
Vibration Test	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) °															
Shock	Appearance : No damage. Impedance : within±10% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Test condition: <table border="1"><thead><tr><th>Type</th><th>Peak Value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (V)/ft/sec</th></tr></thead><tbody><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></tbody></table>	Type	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)/ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
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SMD	50	11	Half-sine	11.3																	
Lead	50	11	Half-sine	11.3																	

Item	Performance	Test Condition
Life test	Appearance: no damage.	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 125±2°C (Bead) Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs.
Load Humidity	Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2 hrs.
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: -40±2°C 30±5 min. Step2: 25±2°C ≅ 0.5min Step3: +125±2°C 30±5min. (Bead) Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.
Insulation Resistance	IR>1GΩ	Chip Inductor Only Test Voltage:100±10%V for 30Sec.

****Derating Curve**

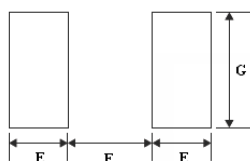
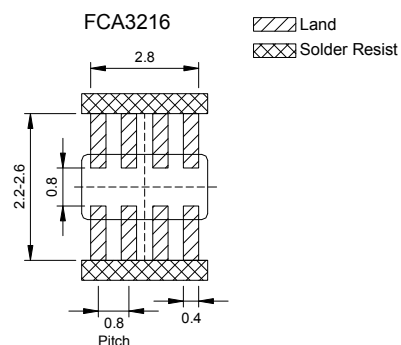
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 85°C, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



6.Soldering and Mounting

6-1. Recommended PC Board Pattern

Chip Size						Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
FCB	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.35	0.30	0.40
	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
HCB	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	1.00	1.45
GHB		2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30			
FCI	3216	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	1.05	2.20	1.80
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
HCI		4532	4.5±0.20	3.20±0.20	1.50±0.20			



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note.

If wave soldering is used, there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

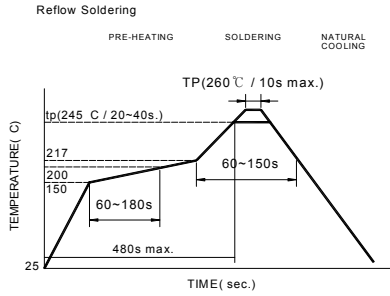
6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Referred to J-STD-020C)

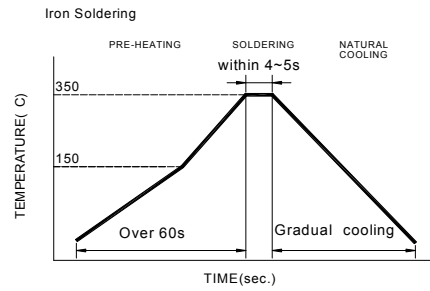
6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.



Reflow times: 3 times max
Fig.1

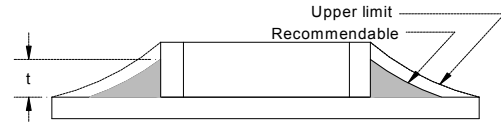


Iron Soldering times : 1 times max
Fig.2

6-2.3 Solder Volume:

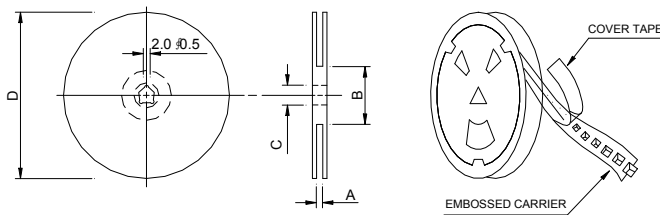
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7.Packaging Information

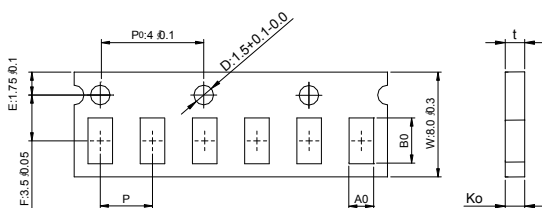
7-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	10±1.5	50 or more	13±0.2	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper

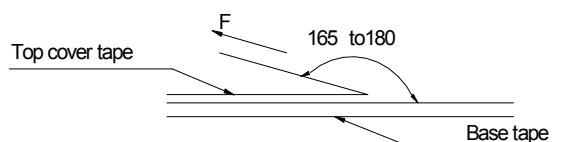


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
060303	0.70±0.06	0.40±0.06	0.45max	2.0±0.05	0.45max

7-3. Packaging Quantity

Chip Size	060303
Chip / Reel	15000
Inner box	75000
Middle box	375000
Carton	750000

7-4. Tearing Off Force



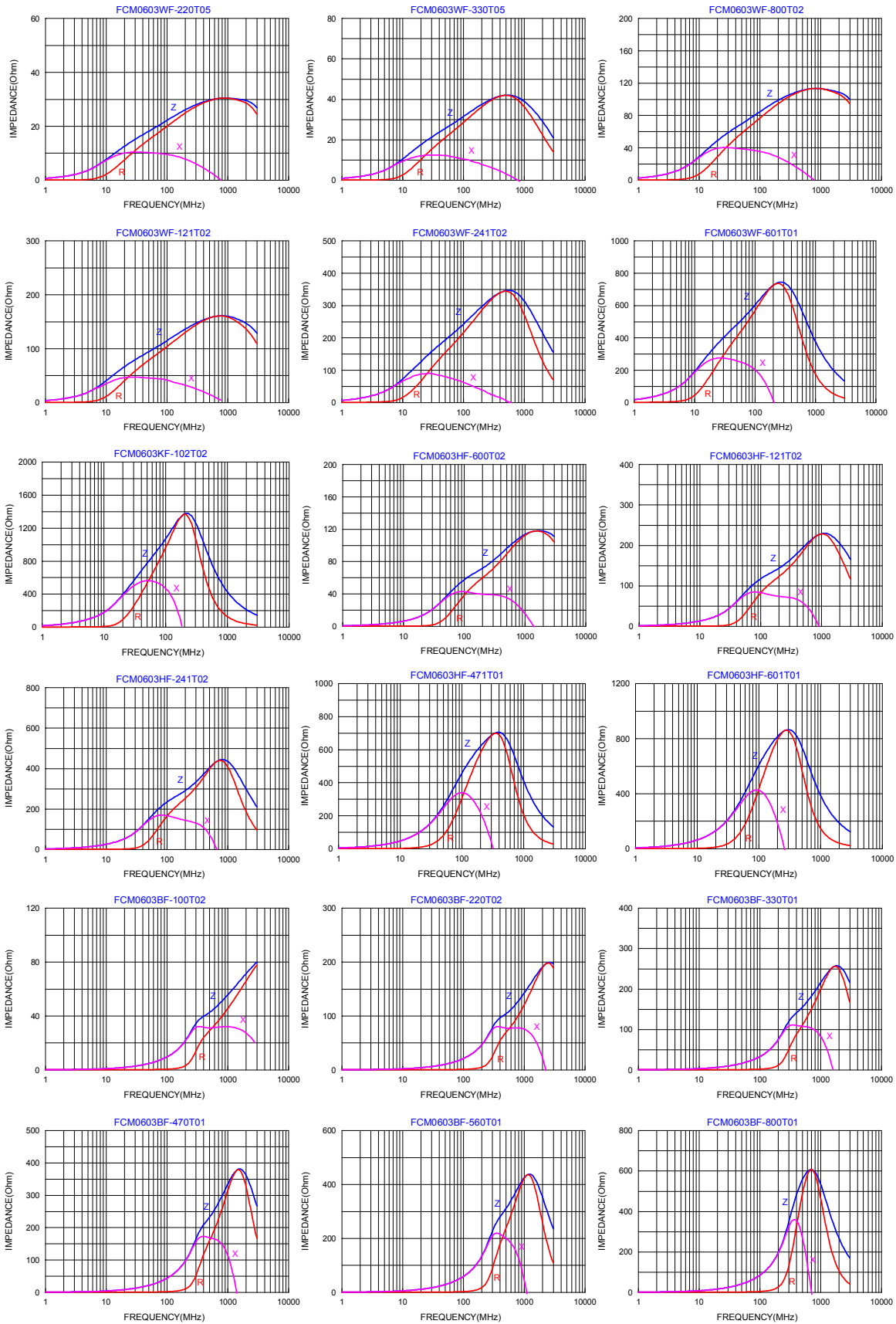
The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
 - To maintain the solder ability of terminal electrodes:
 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
 3. Recommended products should be used within 12 months from the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

Impedance Frequency Characteristics(Typical)



Impedance Frequency Characteristics(Typical)

